IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				under both le	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information					
Supplier Inforn	nation															
Company name* Company unique l				que ID			Unique ID Authority					Response Date*				
onsemi												2024-05-10				
Contact Name			Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-Stewa	ards	Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com					
uthorized Represe	entative*	Title - Representative			I	Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requesto	quester Item Number Mfr Item		n Number Mfr Item Name				Effective Date Version Manual		Manufactu	Manufacturing Site		Veight [*]	*	UOM	Unit Type	
				2KB SPI SER CMOS EEPROM TSSOP8 - Low Vcc range		2024-05-10		PH1		3	31.2 m		mg	Each		
Janufacturing	Proccess Informatio	n														
Terminal	Terminal Plating / Grid Array Material		Terminal Base Alloy J		-STD-020 MSL Rating		Peak Process Body Temperat		ure Max Time at Peak 7		Temperatu	Temperature Number of Reflow Cycles		les		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy		1		260		С	30 seco		secono	ls 3	i		
Comments							-						-			
evel 1 - maximum t	ime at peak temperature	during sol	dering is 10-3	0 seconds					<u> </u>							
or more informati	on regarding material co	nposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a		
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per t	he definition above except for defined Rol	IS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.66	mg	Supplier	Silicon (Si)	7440-21-3		0.66	mg
Die Attach	0.12	mg		Epoxy resin	proprietary data		0.012	mg
			Supplier	Silver (Ag)	7440-22-4		0.096	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.012	mg
Lead Frame	10.96	mg	Supplier	Zinc (Zn)	7440-66-6		0.0132	mg
			Supplier	Iron (Fe)	7439-89-6		0.2576	mg
			Supplier	Copper (Cu)	7440-50-8		10.686	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0033	mg
Mold Compound-Black	19.21	mg		Epoxy resin	proprietary data		1.4408	mg
			Supplier	Phenolic Resin	Proprietary Data		0.4802	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.4408	mg
			Supplier	Carbon Black (C)	1333-86-4		0.096	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		15.7522	mg
Plating	0.12	mg	Supplier	Palladium (Pd)	7440-05-3		0.006	mg
			В	Nickel (Ni)	7440-02-0		0.108	mg
			Supplier	Gold (Au)	7440-57-5		0.006	mg
Wire Bond - Au	0.13	mg	Supplier	Gold (Au)	7440-57-5		0.13	mg